

# SMQ32SL Series Material Declaration

Total Weight: 126.6 mg



Part	Weight of parts (mg)	Content substance	CAS No	Content (mg)	Content (ppm)	
Cap	24.41	C7521R	Copper (Cu)	7440-50-8	13.66	107858
			Nickel(Ni)	7440-02-0	3.71	29324
			Zinc (Zn)	7440-66-6	3.94	31102
			Manganese (Mn)	7439-96-5	0.03	219
			Iron(Fe)	7439-89-6	0.00	17
			PLATING	Nickel(Ni)	7440-02-0	3.07
ENCLOSURE	13.45	HEADER	Nickel(Ni)	7440-02-0	2.03	16027
			Iron(Fe)	7439-89-6	2.87	22672
			Cobalt(Co)	7440-48-4	0.02	195
			Manganese (Mn)	7439-96-5	0.02	156
			Chromium (Cr)	7440-47-3	0.00	39
			GLASS	Silicon oxide(SiO <sub>2</sub> )	14808-60-7	2.82
		TERMINAL	Iron(Fe)	7439-89-6	0.99	7834
			Nickel(Ni)	7440-02-0	0.53	4214
			Cobalt(Co)	7440-48-4	0.31	2470
			Manganese (Mn)	7439-96-5	0.00	7
			PLATING	Lead (Pb)*	7439-92-1	3.73
BLANK	2.40	ELECTRODE	Tin (Sn)	7440-31-5	0.12	911
			Silicon oxide(SiO <sub>2</sub> )	14808-60-7	2.36	18645
			Chromium (Cr)	7440-47-3	0.00	30
			Silver(Ag)	7440-22-4	0.03	240
SOLDER	2.86		Lead (Pb)*	7439-92-1	2.65	20958
			Tin (Sn)	7440-31-5	0.15	1192
			Silver(Ag)	7440-22-4	0.06	434
BOND	2.98		Silicone Resin DA 6503	-	2.98	23533
LEAD FRAME	13.73	MF202R	Copper (Cu)	7440-50-8	12.42	98115
			Tin (Sn)	7440-31-5	0.25	2011
			Nickel(Ni)	7440-02-0	0.04	302
			Phosphorus (P)	7723-14-0	0.01	101
			Tin (Sn)	7440-31-5	0.97	7668
		PLATING	Copper (Cu)	7440-50-8	0.03	237
MOLD	66.8	E7000	LCP	60088-52-0	46.76	369260
			FIBER GLASS	65997-17-3	20.04	158254

\* Exemptions from RoHS: No 7 (a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)